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PATENTS

Attorney Docket No.: ELM-2 DIV. 6

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Glenn J. Leedy
Application No. : 10/614,067 Confirmation No.: 8117
Filed : July 3, 2003
For : THREE DIMENSIONAL STRUCTURE INTEGRATED
CIRCUIT
Group Art Unit : 2822
Examiner : Pamela E. Perkins

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97,
applicant wishes to call the attention of the Examiner to the
following documents:

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The aforementioned references are listed on the accompanying Form PTO/SB/08 (submitted in duplicate). Pursuant to 37 C.F.R. 1.98 (a)(2), applicant is not submitting copies of the aforementioned U.S. patent document references. Copies of the aforementioned Foreign Patent Documents and Non-Patent Literature Documents are enclosed herewith.

Applicant reserves the right to establish the patentability of the claimed invention over any of the information provided herewith, and/or to prove that this information may not be prior art, and/or to prove that this information may not be enabling for the teachings purportedly offered.

The aforementioned U.S. Patent Documents identified by (1) were cited in an Office Action mailed on October 18, 2005 in co-pending commonly assigned U.S. Patent Application No. 10/143,200. Documents identified by (2) were cited in an Office Action mailed on November 17, 2005 in co-pending commonly assigned U.S. Patent Application No. 10/742,057. Documents identified by (3) were cited in an Office Action mailed on December 7, 2005 in co-pending commonly assigned U.S. Patent Application No. 10/766,557. The Document identified by (4) was cited in an Office Action mailed on December 13, 2005 in co-pending commonly assigned U.S. Patent Application No. 10/742,282. The document identified by (5) was cited in an Office Action mailed on December 19, 2005 in co-pending commonly assigned U.S. Patent Application No. 10/379,820. The U.S. Patent Documents and

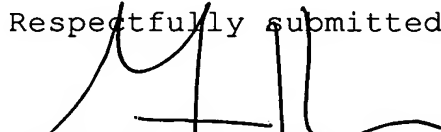
Nonpatent Literature Documents identified by (6) were cited in an Office Action mailed on January 26, 2006 in co-pending commonly assigned U.S. Patent Application No. 10/741,647.

It is respectfully requested that these references be: (1) fully considered by the Patent and Trademark Office during the examination of this application; and (2) printed on any patent which may issue on this application. Applicant requests that a copy of Form PTO-SB/08, as considered and initialed by the Examiner, be returned with the next communication.

This Statement is submitted concurrently with a request for continued examination under 37 C.F.R. §1.114. Pursuant to 37 C.F.R. §1.97(b)(4), applicant believes no fee is due in connection with this statement. However, if for any reason a fee is due, the Director is hereby authorized to charge payment of any fees required in connection with this Statement, or to credit any overpayment of the same, to Deposit Account No. 06-1075 (Order No.: 001202-0132). A duplicate copy of this Statement is enclosed herewith.

An early and favorable action is respectfully requested.

Respectfully submitted,



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PTO/SB/08a/b (08-03)

Approved for use through 07/31/2006. OMB 0651-0031
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| Substitute for form 1449A/B/PTO | | | | Complete if Known | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary) | | | | Application Number | 10/614,067 (Conf. No. 8117) |
| | | | | Filing Date | July 3, 2003 |
| | | | | First Named Inventor | Leedy |
| | | | | Art Unit | 2822 |
| | | | | Examiner Name | Pamela Perkins |
| Sheet | 1 | of | 3 | Attorney Docket Number | ELM-2 Div. 6 |

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| Examiner Initials* | Cite No. ¹ | Document Number | Publication Date MM-DD-YYYY | Name of Patentee or Applicant of Cited Document | Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear |
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| Substitute for form 1449A/B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i> | | | Complete if Known | | |
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| | | | Art Unit | 2822 | |
| | | | Examiner Name | Pamela Perkins | |
| Sheet | 2 | of | 3 | Attorney Docket Number | ELM-2 Div. 6 |

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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